

# GSMS05N15

## 150V N-Channel Enhancement Mode MOSFET

### Product Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

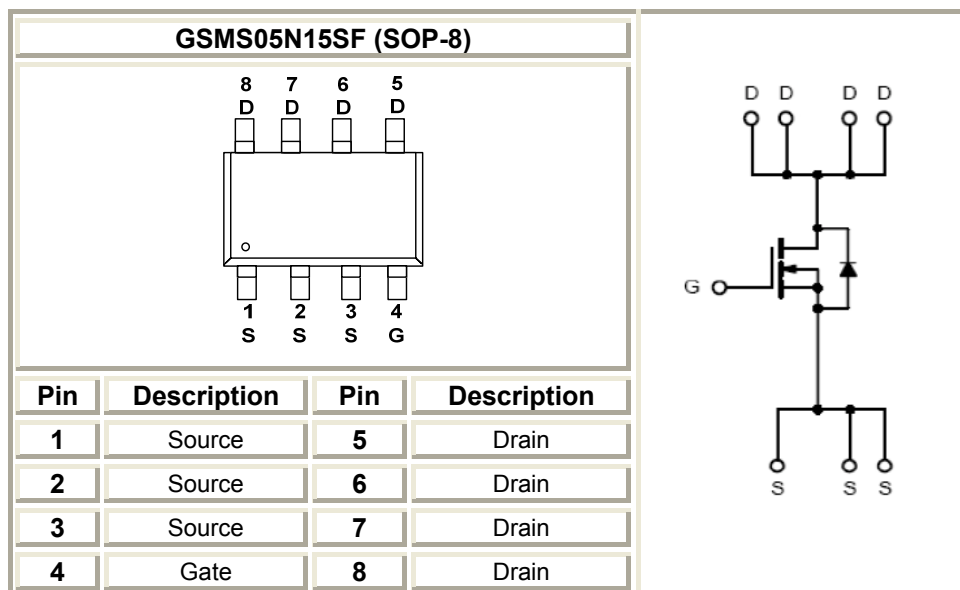
### Features

- 150V, 5A,  $R_{DS(ON)}=65m\Omega@V_{GS}=10V$
- $V_{GS}$  Guarantee  $\pm 25V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- SOP-8 package design

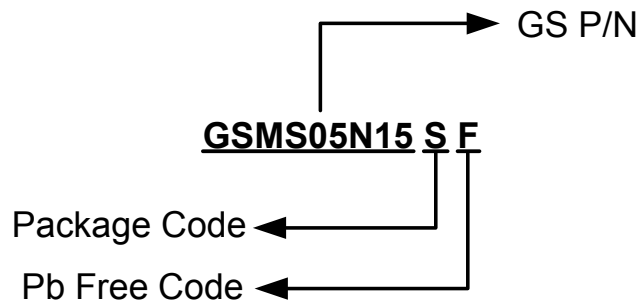
### Applications

- Notebook
- Load Switch
- LED applications
- Li battery pack application

### Packages & Pin Assignments

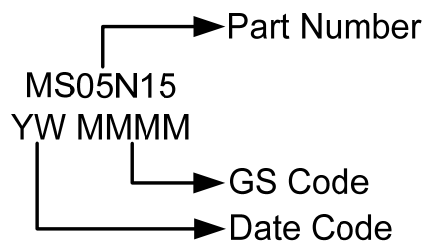


## Ordering Information



Part Number	Package	Quantity
GSMS05N15SF	SOP-8	4000 PCS

## Marking Information



## Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  unless otherwise noted)

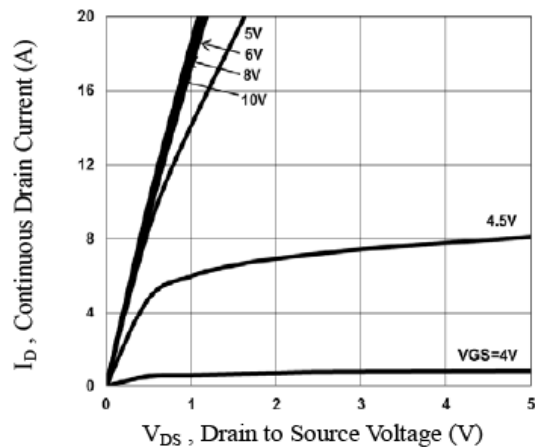
Symbol	Parameter	Typical	Unit
$V_{DSS}$	Drain-Source Voltage	150	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	V
$I_D$	Continuous Drain Current	$T_A=25^\circ\text{C}$	5
		$T_A=100^\circ\text{C}$	3.2
$I_{DM}$	Pulsed Drain Current	20	A
$P_D$	Power Dissipation	3.6	W
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	35	$^\circ\text{C/W}$

## Electrical Characteristics

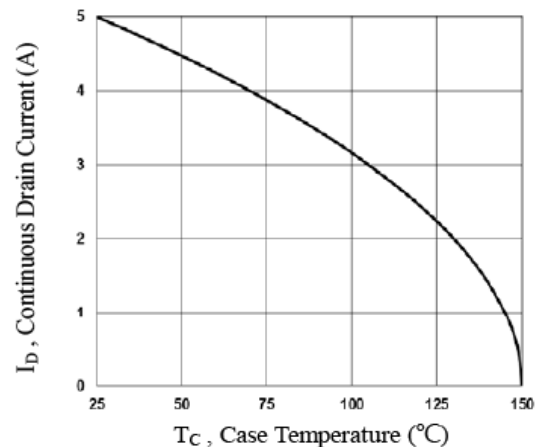
( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	150			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0		4.0	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient	$V_{DS}=V_{GS}, I_D=250\mu A$		-2.5		mV/°C
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$		0.02		V/°C
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 25V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=120V, V_{GS}=0V$			1	uA
		$V_{DS}=120V, V_{GS}=0V$ , $T_J=125^\circ\text{C}$			30	
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=10V, I_D=5A$		52	65	mΩ
		$V_{GS}=5V, I_D=3A$		60	80	
$V_{SD}$	Diode Forward Voltage	$I_S=1A, V_{GS}=0V$			1.3	V
$t_{rr}$	Reverse Recovery Time	$I_S=1A, V_{GS}=0V$ , $di/dt=100A/\mu s$		55		ns
$Q_{rr}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$		130		nC
<b>Dynamic</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=75V$ , $V_{GS}=0V, f=1\text{MHz}$		1340		pF
$C_{oss}$	Output Capacitance			134		
$C_{rss}$	Reverse Transfer Capacitance			60		
$Q_g$	Total Gate Charge	$V_{DS}=75V$ , $V_{GS}=10V, I_D=4.1A$		30		nC
$Q_{gs}$	Gate-Source Charge			7		
$Q_{gd}$	Gate-Drain Charge			10		
$t_{d(on)}$	Turn-On Time	$V_{DD}=75V, I_D=4.1A$ , $V_{GS}=10V, R_G=6\Omega$		15		ns
$t_r$				10		
$t_{d(off)}$	Turn-Off Time			34		
$t_f$				12		

## Typical Performance Characteristics

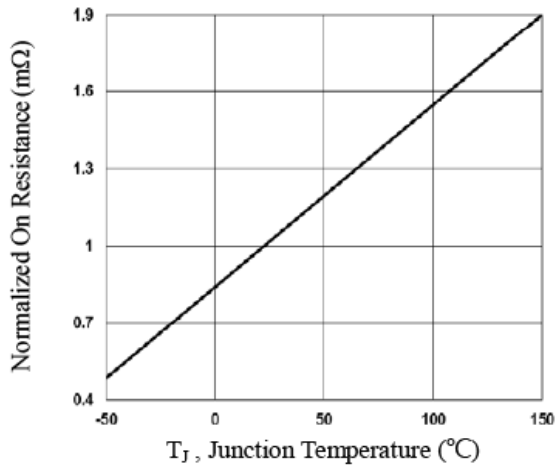


**Fig.1 Output Characteristics**

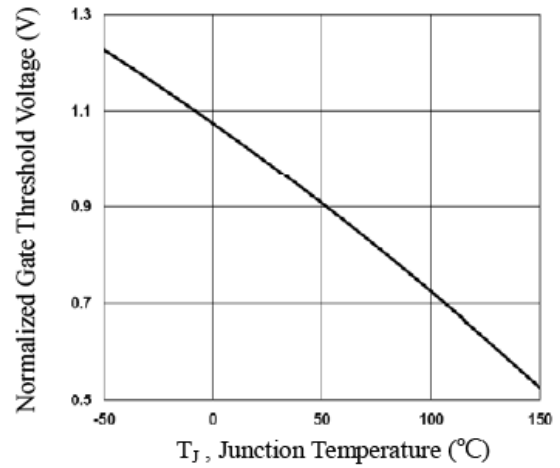


**Fig.2 Continuous Drain Current vs.  $T_C$**

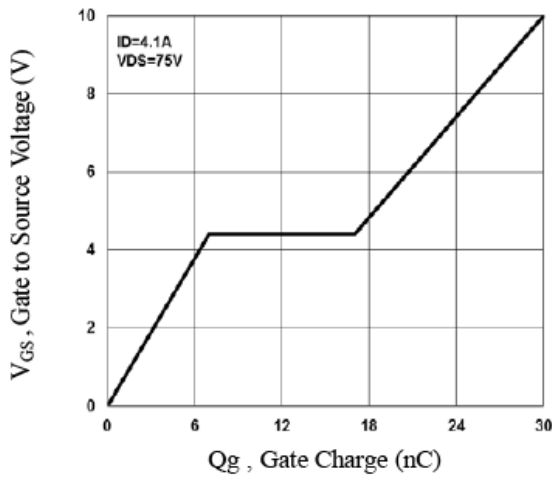
## Typical Performance Characteristics (Continue)



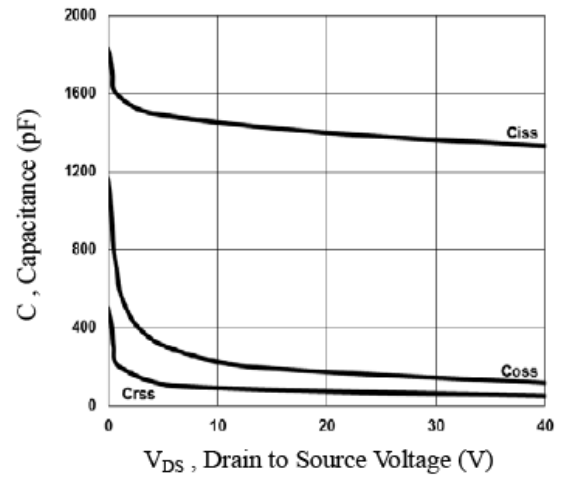
**Fig.3 Normalized RDSON vs.  $T_J$**



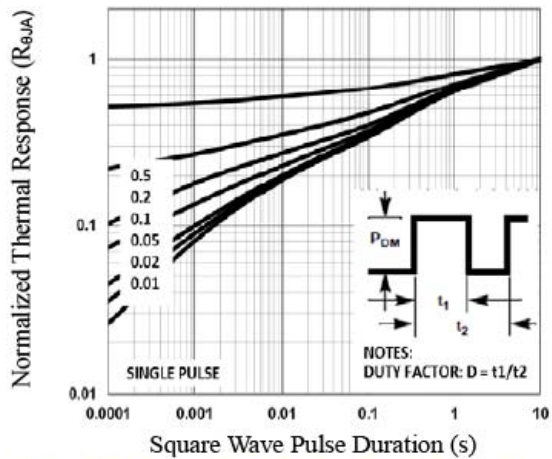
**Fig.4 Normalized  $V_{th}$  vs.  $T_J$**



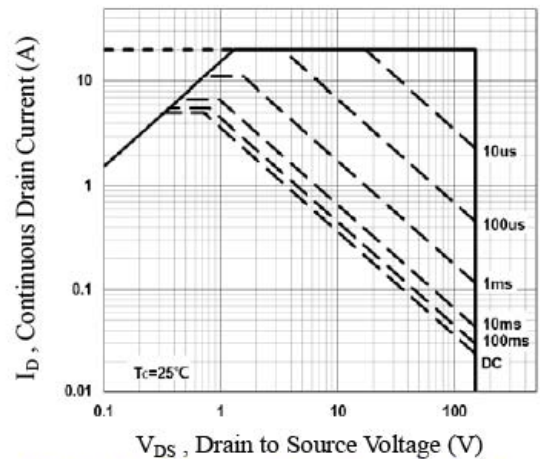
**Fig.5 Gate Charge Waveform**



**Fig.6 Capacitance Characteristics**



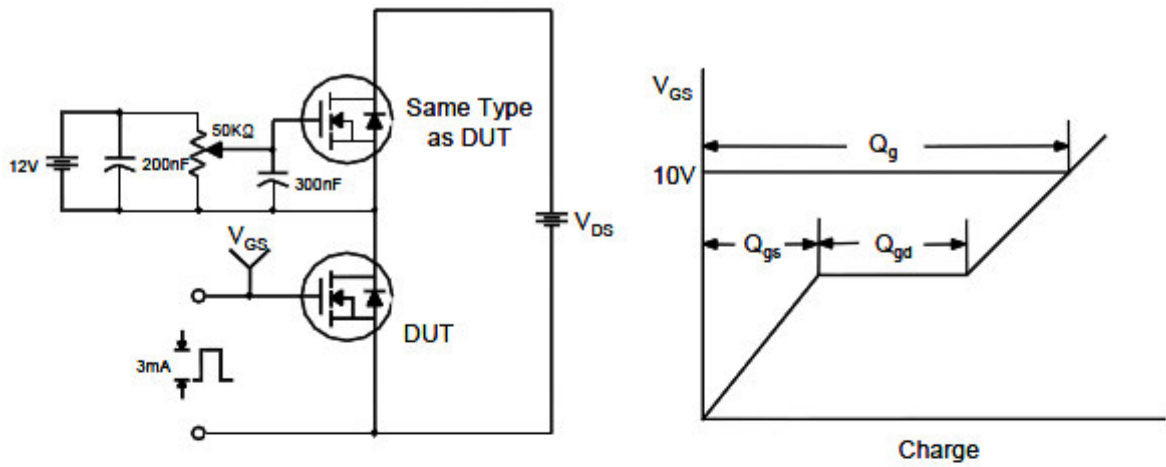
**Fig.7 Normalized Transient Impedance**



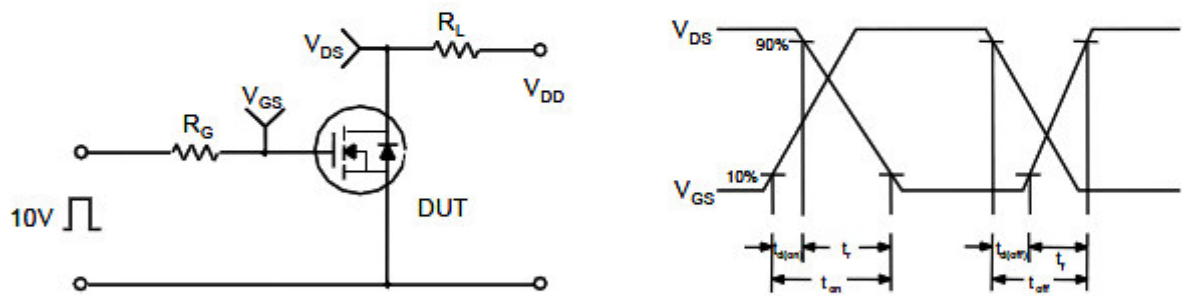
**Fig.8 Maximum Safe Operation Area**

## Typical Characteristics

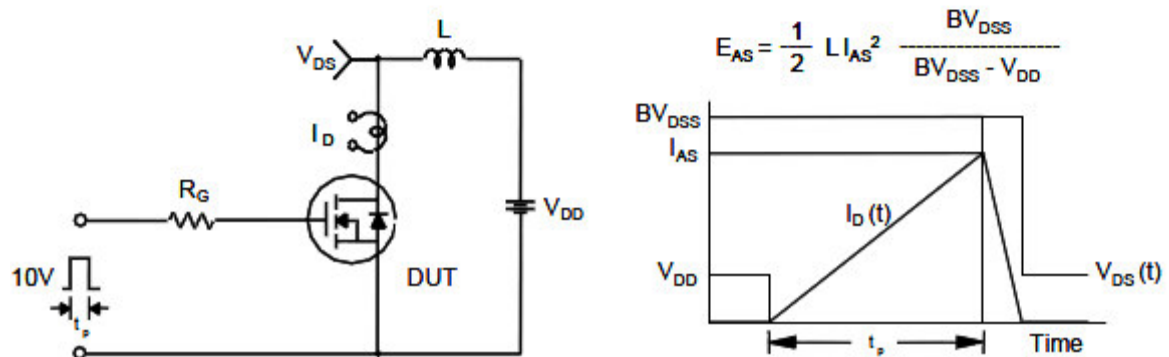
### Gate Charge Test Circuit & Waveform



### Resistive Switching Test Circuit & Waveforms

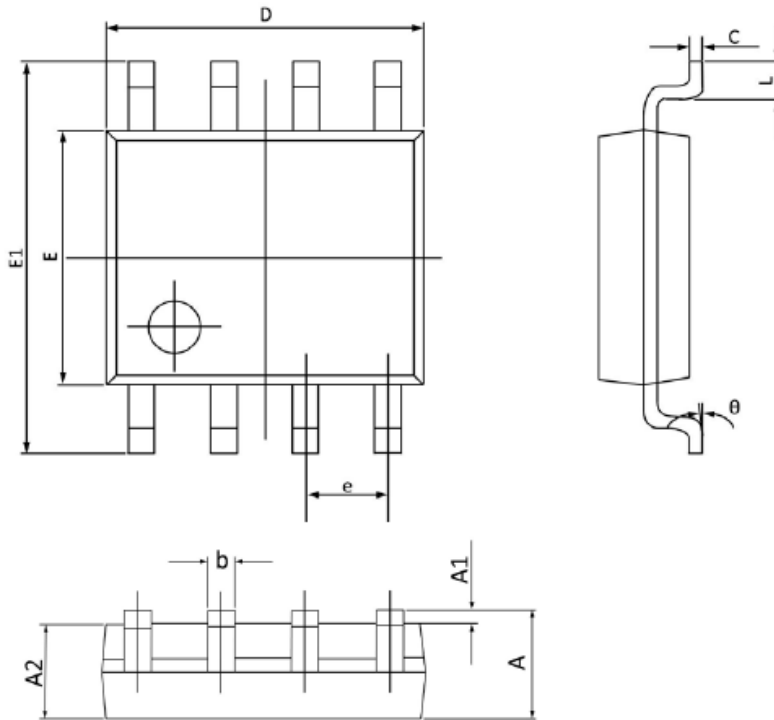


### Unclamped Inductive Switching Test Circuit & Waveforms



## Package Dimension

### SOP-8



### Dimensions

Symbol	Millimeters		Inches	
	Min	Max	Min	Max
<b>A</b>	1.35	1.75	0.053	0.069
<b>A1</b>	0.10	0.25	0.004	0.010
<b>A2</b>	1.35	1.55	0.053	0.061
<b>b</b>	0.33	0.51	0.013	0.020
<b>c</b>	0.17	0.25	0.006	0.010
<b>D</b>	4.70	5.10	0.185	0.200
<b>E</b>	3.80	4.00	0.150	0.157
<b>E1</b>	5.80	6.20	0.228	0.244
<b>e</b>	1.27(BSC)		0.050(BSC)	
<b>L</b>	0.40	1.27	0.016	0.050
<b>θ</b>	0°	8°	0°	8°

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## CONTACT US

GS Headquarter	
	4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd Neihu District Taipei City 114, Taiwan (R.O.C)
	886-2-2657-9980
	886-2-2657-3630
	sales_twn@gs-power.com

Shenzhen Branch(China)	
	1113 B Building, Happiness Washington, Baoan Nan Road, Luohu District, Shenzhen City, China
	0755-22208941
	sales_cn@gs-power.com

RD Division	
	824 Bolton Drive Milpitas. CA. 95035
	1-408-457-0587